

Copper

SLOTOCOUP BV 110

Copper SLOTOCOUP BV 110 is used for the production of HDI boards in order to

- fill blind micro vias with copper
- pattern plating
- metallize through-holes

in a one-step process.

Copper SLOTOCOUP BV 110 deposits very bright coatings with outstanding levelling quality, excellent metal distribution and throwing power.

Copper SLOTOCOUP BV 110 can be operated in vertical continuous plating lines as well as in standard vertical plating lines.

The metal distribution can be adapted to the printed circuit board's surface geometry by regulation of the current density and electrolyte composition.

Copper SLOTOCOUP BV 110 is operated with three liquid additives.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read these instructions carefully and follow recommendations given. We reserve the right to make technical changes as necessary. In the interests of safety, please pay attention to the R- and S-phrases on the labels of the containers. The minimum shelf life of the additives is printed on the label of the container. The current IMDS number of the layer deposited from the process can be found on the internet at www.schloetter.com/downloads.

For the storage of chemical products only the TRGS 514 and TRGS 515 regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) is only valid **for transportation** and must not be applied to storage.

